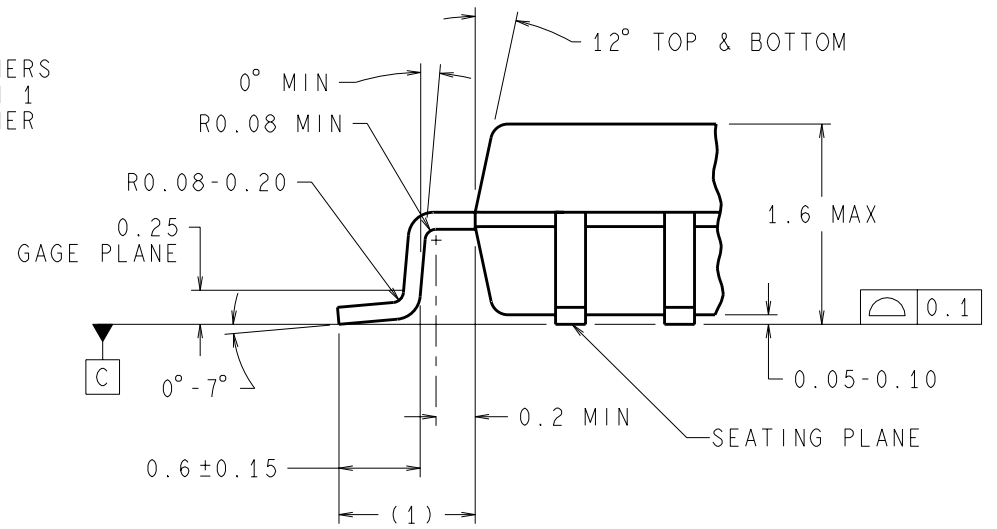
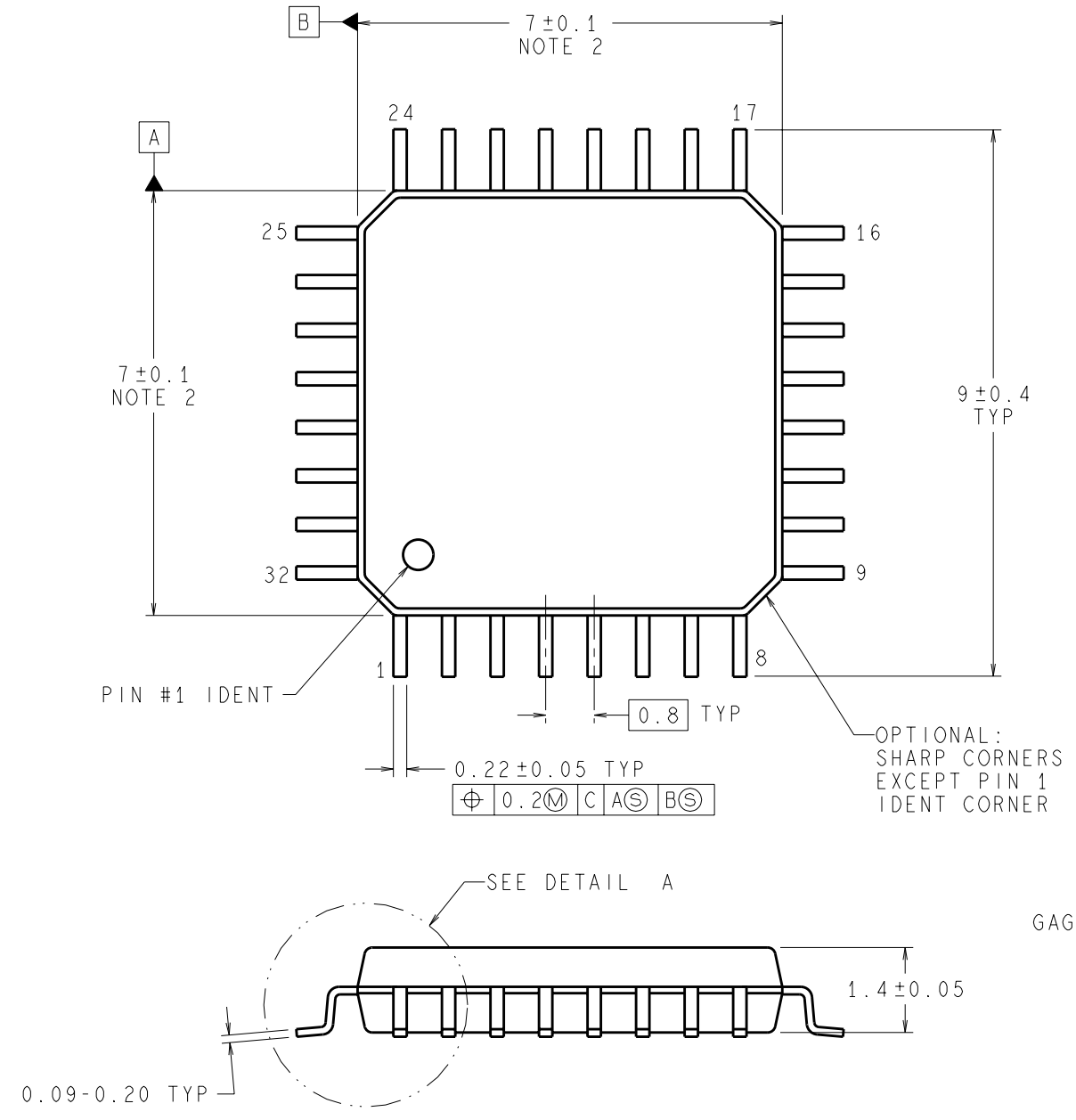


REVISIONS				
LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
D	ADD CHAMFERS ON PKG CORNERS & OPT NOTE; REDRAW ON PRO/E	10898	03/21/1995	TL/HJK
E	TITLE: LOFP WAS POFP; UPDATE NOTE 3; ADD GEOMETRIC TOLERANCE	12317	12/03/1999	ACS/MS/RW



DETAIL A
TYP, SCALE: 30X

DIMENSIONS ARE IN MILLIMETERS

- NOTES: UNLESS OTHERWISE SPECIFIED
- STANDARD LEAD FINISH:
7.62 MICROMETERS MINIMUM SOLDER PLATING (85/15)
THICKNESS ON ALLOY 42/COPPER.
 - DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.
MAXIMUM ALLOWABLE MOLD PROTRUSION 0.15mm PER SIDE.
 - REFERENCE JEDEC REGISTRATION MS-026, VARIATION BBA,
DATED FEB 1999.

APPROVALS		DATE		 National Semiconductor 2900 Semiconductor Dr., Santa Clara, CA 95052-8090	
DRAWN T. LEQUANG		03/21/1995			
DFTG. CHK. THANH LEQUANG		12/06/1999			
ENGR. CHK. RANDALL WALBERG		12/06/1999		LQFP, JEDEC METRIC, 7 X 7 X 1.4mm, 32 LEAD	
 PROJECTION INCH [MM]		SCALE N/A	SIZE C		
FORMERLY:				SHEET 1 of 1	